IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

Shibaek Nam; Oseob Jeon; and Chulho Heo

Assignee:

Fairchild Semiconductor Corporation

Title:

Semiconductor Device Having Multi-Chip Package Structure

Serial No.:

10/038,714

Filing Date:

January 2, 2002

Examiner:

Pershelle L. Greene

Art Unit:

2826

Docket No.:

M-11590 US

San Francisco, California October 11, 2002

COMMISSIONER FOR PATENTS Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

This is a response to the Office Action dated August 13, 2002, which requires a restriction election to be made between the following groups of claims:

Group I: Claims 1-36 identified in the Office Action as drawn to a semiconductor device having a multi-chip package.

Group II: Claims 37-60 identified in the Office Action as drawn to a method of manufacturing a semiconductor device having a multi-chip package.

Applicants hereby elect the claims of Group I (claims 1-36) without traverse.

Applicants reserve the right to re-present the claims of the non-elected Group II (claims 37-

Applicant respectfully requests that the Application be examined. Should the Examiner wish to discuss the Application, it is requested that the Examiner contact the undersigned at 415-217-6000.

EXPRESS MAIL LABEL NO.:

EV 212 981 853 US

Respectfully submitted,

Philip W. Woo Attorney of Record Reg. No. 39,880